

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/09/2022

Details for "TLV387DBVR"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
TLV387DBVR	SN	Level-2-260C-1 YEAR	Ext-Mfg	DBV 5	2.9x1.6x1.45	19

*Total Device Mass

The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.011253	95.154744	951547	0.059155	592
Precious Metals	Gold	7440-57-5	0.000088	0.744123	7441	0.000463	5
Precious Metals	Palladium	7440-05-3	0.000485	4.101133	41011	0.00255	25
Sub-Total			0.011826	100	1000000	0.062167	622
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.122706	79.999739	799997	0.645046	6450
Thermoplastics	Epoxy	85954-11-6	0.030677	20.000261	200003	0.161264	1613
Sub-Total			0.153383	100	1000000	0.80631	8063
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	6.632428	97.535706	975357	34.865596	348656
Copper and Its Alloys	Iron	7439-89-6	0.153136	2.252	22520	0.805011	8050
Copper and Its Alloys	Phosphorus	7723-14-0	0.001496	0.022	220	0.007864	79
Precious Metals	Silver	7440-22-4	0.004304	0.063294	633	0.022625	226
Zinc and Its Alloys	Zinc	7440-66-6	0.008636	0.127	1270	0.045398	454
Sub-Total			6.8	100	1000000	35.746495	357465
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.04	100	1000000	0.210274	2103
Sub-Total			0.04	100	1000000	0.210274	2103
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	10.148252	86.850005	868500	53.347712	533477
Other Organic Materials	Proprietary Non Halide Flame Retardant	Trade Secret	0.058424	0.5	5000	0.307125	3071
Other Plastics and Rubber	Carbon Black	1333-86-4	0.017527	0.149998	1500	0.092137	921
Thermoplastics	Epoxy	85954-11-6	1.4606	12.499997	125000	7.678137	76781
Sub-Total			11.684803	100	1000000	61.425111	614251
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.332832	100	1000000	1.749644	17496
Sub-Total			0.332832	100	1000000	1.749644	17496
Total			19.022844			100	1000000

Important Note

The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.

The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.

[See Glossary of Terms for more details.](#)

Important Part Information

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI's or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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For further environmental statements, please go to www.ti.com/ecoinfo

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RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.